

Features

Frequency range : 24MHz to 54MHz
 Ultra compact and thin
 AuSn sealing, ceramic SMD package
 External dimensions (mm)
 L : 1.2 x W : 1.0 x H : 0.3
 RoHS compliant & Pb free

Applications

BT, BLE, W-LAN, NFC
 SiP modules
 Mobile phone, Wearables
 Internet of Things (IoT)
 Portable consumer products

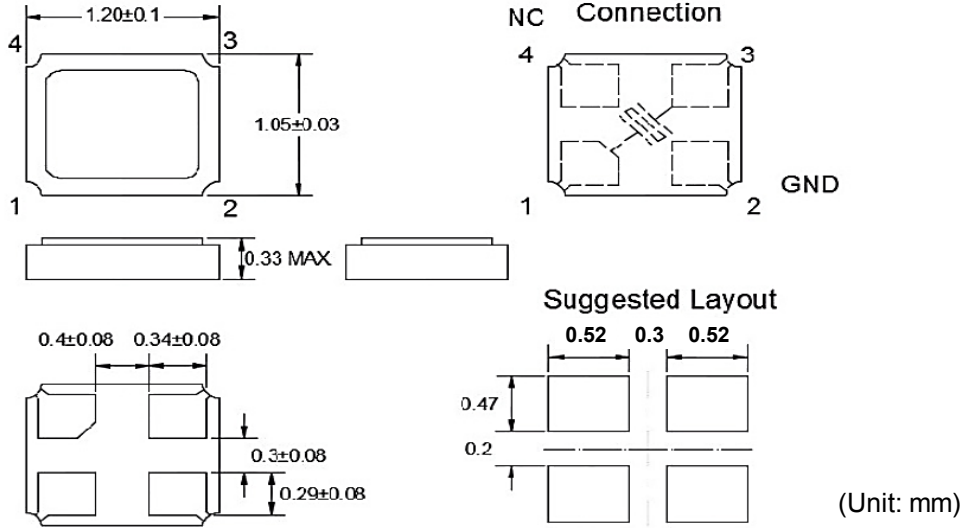
Electrical Characteristics

Item		8J	Conditions
Frequency Range	F_0	24MHz ~ 54MHz	
Frequency Tolerance	F_{tol}	±30ppm, ±20ppm, ±10ppm	at 25°C
Frequency Stability over Operating Temperature Range (refer to 25°C)	F_{stab}	±30 ppm	-20°C ~ +70°C
		±20 ppm	
		±10 ppm	
		±10 ppm	-30°C ~ +85°C
		±30 ppm	-40°C ~ +85°C
		±20 ppm	
Operating Temperature Range	T_{OTR}	-20°C ~ +70°C	
		-40°C ~ +85°C	
		-40°C ~ +125°C	
Shunt Capacitance	C_0	3pF Max.	
Drive Level	D_L	1 ~ 100μW (50μW Typ.)	
Load Capacitance	C_L	6pF, 8pF, 10pF, 12pF	
Aging	F_{aging}	±3 ppm Max.	at 25°C ± 3°C, first year
Storage Temperature Range	T_{STR}	-55°C ~ +125°C	

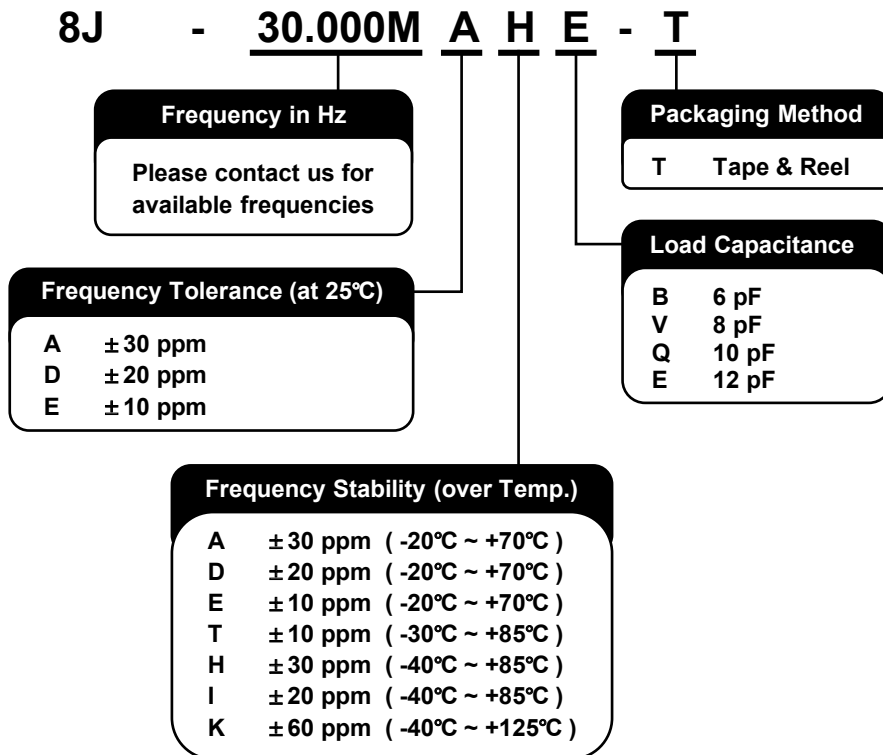
Motional Resistance (ESR)

Fundamental	
24 ~ 30 MHz	150Ω Max.
30 ~ 54 MHz	100Ω Max.

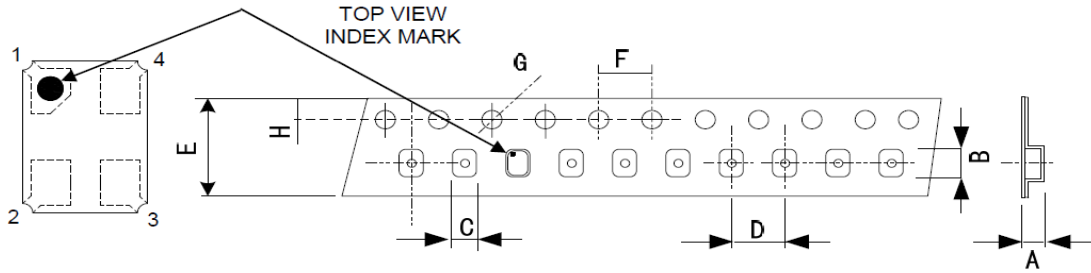
Dimensions



Ordering Information

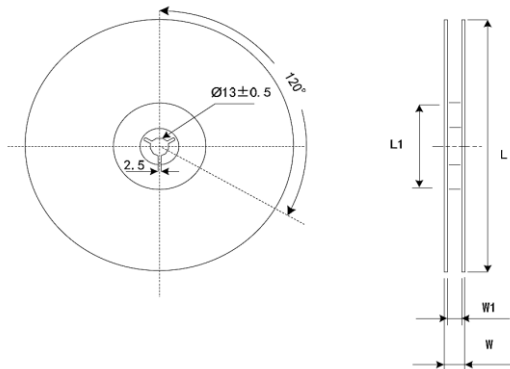


Packing



DIMENSIONS	A	B	C	D	E	F	G	H
	0.45	1.30	1.10	4.00	8.00	4.00	1.55	1.75
	±0.05	±0.05	±0.05	±0.10	±0.20	±0.10	±0.05	±0.10

(Unit: mm)



DIMENSIONS	L	L1	W	W1
	178	60.2	11.5	8
	±1.00	±0.50	±0.2	+1/-0

(Unit: mm)

Reflow Profile

Solder melting point : 220°C ± 10°C, 60 sec. Min.

Peak temperature : 260°C ± 10°C, 10 sec. Min.

